

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S241	77	(bond adj pad adj thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/27 12:07
S242	3	S241 and (gap near5 height)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/27 12:08
S243	16	((flip adj chip) near5 (gap near5 height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/27 12:11
S249	6	(chip same board same (gap adj height) same (solder near5 (ball or interconnect or interconnect or array or grid)) same (underfill or encapsulant or encapsulat\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/27 12:18
S259	94	((underfill or underfill\$3 or encapsulant or encapsulat\$3) with (before or after or prior or post or pre) with (attach\$3 or attachment or plac \$3 or align\$3) with (gap or space) with (chip or board or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/27 13:20

S266	69	((underfill or encapsulant or encapsulat\$3) near5 (filler near5 (particle adj size)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/04/28 10:39
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4/29/2008 2:36:14 PM

C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10711501 solder interconnect array with optimal mechanical integrity 228-215 FOAM 10-03-2006.wsp